

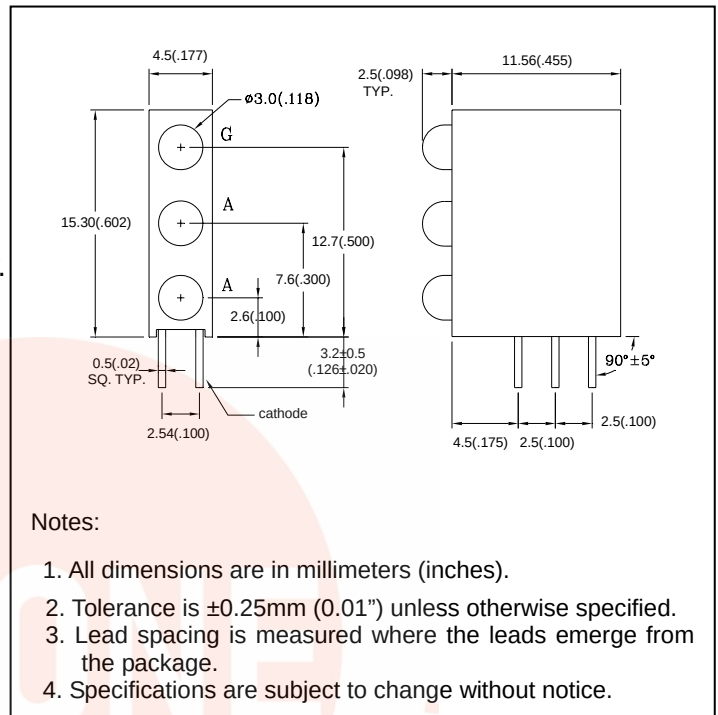
● Features:

1. Chip material: GaP/GaP (Green)
and GaAsP/GaP (Amber)
2. Emitted color : Green and Amber
3. Lens Appearance : Green Diffused
and Orange Diffused
4. Designed for ease in circuit board assembly.
5. Black case enhance contrast ratio.
6. Solid state light source.
7. Reliable and rugged.
8. This product don't contained restriction
substance, compliance RoHS standard.

● Applications:

1. TV set
2. Monitor
3. Telephone
4. Computer
5. Circuit board

● Package dimensions



● Absolute Maximum Ratings(Ta=25°C)

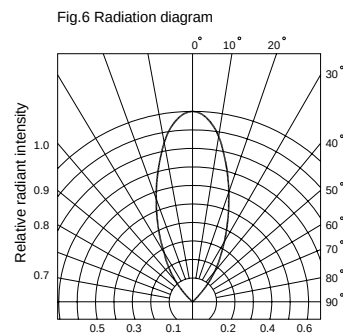
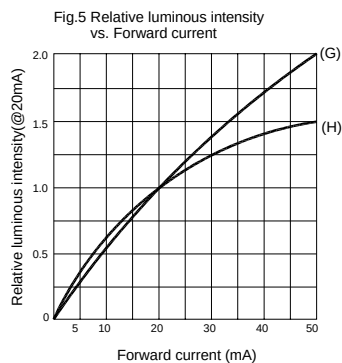
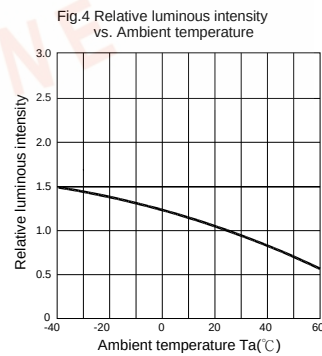
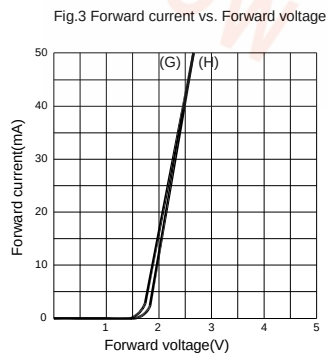
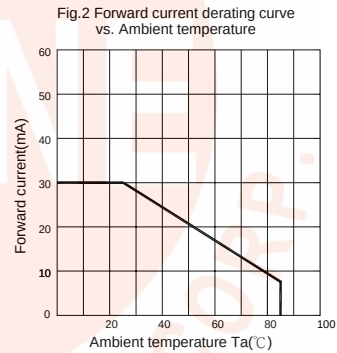
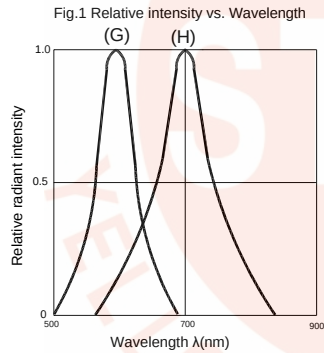
Parameter	Symbol	Green	Amber	Unit
Power Dissipation	Pd	80	80	mW
Forward Current	I _F	30	30	mA
Peak Forward Current ^{*1}	I _{FP}	150	150	mA
Reverse Voltage	V _R	5		V
Operating Temperature	T _{opr}	-40°C~85°C		
Storage Temperature	T _{stg}	-40°C~100°C		
Soldering Temperature	T _{sol}	260°C max(for 5 seconds)		
Hand Soldering Temperature	T _{sol}	350°C max(for 3 seconds)		

^{*1}Condition for I_{FP} is pulse of 1/10 duty and 0.1msec width.

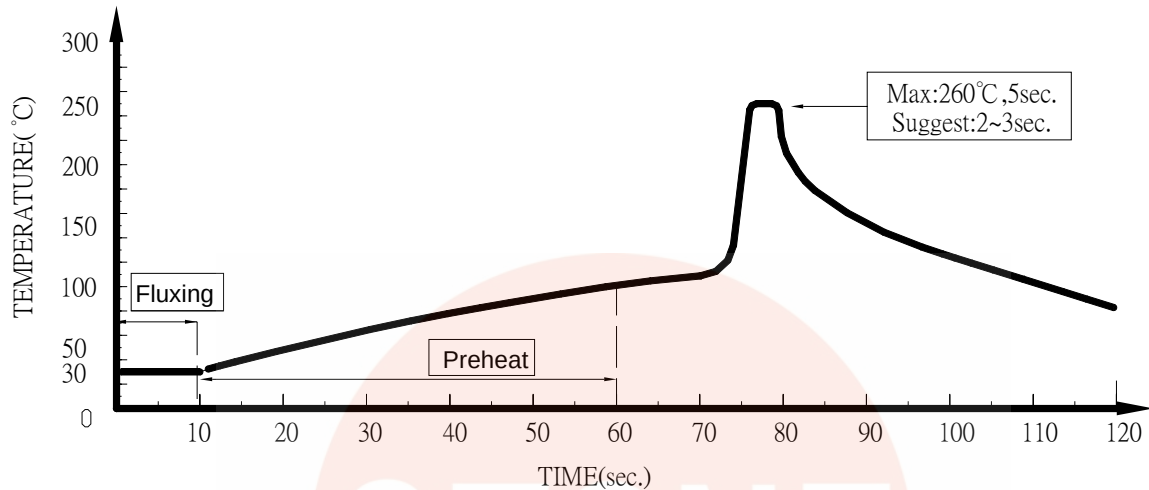
● **Electrical and optical characteristics(Ta=25°C)**

Parameter	Symbol	Condition	Color	Min.	Typ.	Max.	Unit
Forward Voltage	V_F	$I_F=20\text{mA}$	Green Amber	-	2.2 2.1	2.6 2.6	V
Luminous Intensity	I_v	$I_F=20\text{mA}$	Green Amber	-	35 30	-	mcd
Reverse Current	I_R	$V_R=5\text{V}$	Green Amber	-	-	100	μA
Peak Wave Length	λ_p	$I_F=20\text{mA}$	Green Amber	-	568 610	-	nm
Dominant Wave Length	λ_d	$I_F=20\text{mA}$	Green Amber	560 600	- -	574 615	nm
Spectral Line Half-width	$\Delta\lambda$	$I_F=20\text{mA}$	Green Amber	-	30 35	-	nm
Viewing Angle	$2\theta_{1/2}$	$I_F=20\text{mA}$	Green Amber	-	45	-	deg

● **Typical electro-optical characteristics curves**



● Dip Soldering



1. Please avoid any external stress applied to the lead-frames and epoxy while the LEDs are at high temperature, especially during soldering
2. DIP soldering and hand soldering should not be done more than one time.
3. After soldering, avoid the epoxy lens from mechanical shock or vibration until the LEDs are back to room temperature.
4. Avoid rapid cooling during temperature ramp-down process
5. Although the soldering condition is recommended above, soldering at the lowest possible temperature is feasible for the LEDs

● IRON Soldering

A : Max : 350°C Within 3 sec. One time only.

B : For 3mm LED without flange, if the LED epoxy lays flat on the PCB, the welding condition is 350°C within 2 seconds, one time only.

